

CHEMTRONICS®

Technical Data Sheet

TDS # CWik

Chem-Wik® Rosin

PRODUCT DESCRIPTION

Chem-Wik® Rosin is especially designed for today's heat sensitive electronic components. The lighter mass, pure copper braid construction allows for better thermal conductivity, even at low temperatures. Chem-Wik® Rosin responds as much as 50% faster than conventional desoldering braids. This design minimizes overheating and requires less "contact" pressure for greater operator control. All sizes are coated with a Type "R" organic flux system.

- Requires little or no post solder cleaning
- No corrosive residues
- Optimized weave design for faster wicking and heat transfer
- Halide free
- Minimal risk of heat damage to components and circuit boards

TYPICAL APPLICATIONS

Chem-Wik® Rosin desoldering braid safely removes solder from:

- Thru-hole Components
- Surface Mount Device Pads
- BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Chem-Wik® Rosin	
Flux Type:	Grade WW, Type "R"
Clean-up Required:	No
Military Specifications:	MIL-F-14256F
Shelf Life – 2 years from manufacturer date	
RoHS/WEEE Status	

Part #	Size Inches	Size Metric
2-5L	.030"	.76mm
5-5L	.050"	1.27mm
7-5L	.075"	1.91mm
10-5L	.100"	2.54mm

STATIC DISSIPATIVE PACKAGING

Static Dissipative packaging is available on all 5 foot bobbins. The static dissipative bobbins qualify as electrostatic discharge protective per DOD Standard 1686 and DOD Handbook 263. Meets the static delay rate provision of MIL-B-81705C.

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